

## Palomar Technologies Performs Live Demonstrations at productronica 2015

Carlsbad, CA—November 10, 2015—Palomar Technologies, the world-leading provider of precision microelectronics and optoelectronic packaging systems, today announced they will be performing live demonstrations of the [8000i Wire Bonder](#), [9000 Wedge Bonder](#), and SST International's [Model 5100 Vacuum Pressure Furnace](#) at productronica, held in Munich on November 10-13, 2015. The demonstrations will be taking place at their booth located in Hall B3, Booth 302 at this year's international trade fair for innovative electronics development and production.



*8000i Wire Bonder*



*9000 Wedge Bonder*

Productronica is the perfect platform for live demonstrations of the latest products and solutions, concentrated to a world-wide audience of hybrid manufacturers. It is not only the perfect opportunity for attendees to learn more about and see Palomar Technologies' products in action, but it is also a perfect opportunity for attendees to learn more about SST International's products including their Model 5100. Recently, Palomar Technologies [acquired SST International](#) as a partner in providing customers with total solutions. We look forward to sharing with attendees how our systems complement one another, as well as demonstrating our existing products live.



### About SST International

SST International is widely recognized as an innovative leader in the development and application of microelectronic package assembly equipment and technology. For over fifty years, SST has provided flux-free and [void-free soldering](#), brazing, [glass-sealing](#) and [wafer](#)

[bonding](#) equipment to the worldwide electronics industry. SST's team of leading engineers and technologists are constantly advancing state-of-the-art microelectronic package assembly techniques, processes and equipment. For more information, visit [www.sstinternational.com](http://www.sstinternational.com).

### **About Palomar Technologies**

Palomar Technologies, a former subsidiary of Hughes Aircraft, is the global leader of automated high-accuracy, [large work area die attach](#) and [ball and wedge wire bonding equipment](#) and [precision contract assembly services](#). Customers utilize the products, services and solutions from Palomar Technologies to meet their needs for optoelectronic packaging, complex hybrid assembly and micron-level component attachment. For more information, visit [www.palomartechnologies.com](http://www.palomartechnologies.com).

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